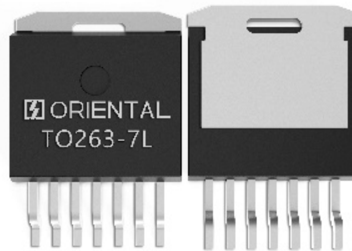
TO263-7L

1、低寄生电感设计：
通过多引脚并联（如 5 根源极引脚并联）和 Kelvin 源极结构，显著降低封装寄生电感（<1nH），减少开关过程中的振荡和噪声，支持高频开关（如 1MHz 以上），降低开关损耗。

1. Low Parasitic Inductance Design
Through the design of multi-pin parallel connection (e.g., 5 source pins in parallel) and Kelvin source configuration, the package parasitic inductance is significantly reduced to below 1nH. This minimizes oscillation and noise during switching, enables high-frequency switching operations (e.g., above 1MHz), and lowers switching losses.



2、高功率密度与散热性能：
基岛面积大，可适配大尺寸芯片，结合鸥翼脚布局和背面散热板，散热效率高，适用于高功率密度场景（如电动汽车充电、光伏逆变器）。

2. High Power Density and Thermal Performance
Boasting a large die pad area that accommodates large-size chips, combined with an gull-wing lead configuration and a backside heat sink, this package delivers high heat dissipation efficiency. It is ideal for high-power-density applications (e.g., electric vehicle charging, photovoltaic inverters).

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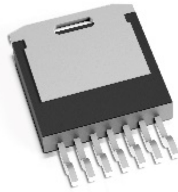

3、高电流承载能力：

漏极引脚接合面积大，源极引脚可多根并联，部分产品脉冲电流能力可达 500A，满足大电流应用需求。

3. High Current-carrying Capacity

The drain pin features a large bonding area, and multiple source pins can be connected in parallel. Some products can achieve a pulsed current capacity of up to 500A, meeting the requirements of high-current applications.

4、表面贴装（SMT）兼容性：

作为贴片式封装，支持自动化生产，焊接简便，相比传统插件封装体积更小，利于系统小型化。

4. Surface Mount Technology (SMT) Compatibility

As a surface-mount package, it supports automated production and enables easy soldering. Compared with traditional through-hole packages, it features a more compact size, facilitating system miniaturization.

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